withwave Versatile RF & MW Test Solutions

High Density Board Connector

Withwave's SMPM Connectors are covering wide frequency ranges from RF to Microwave with excellent frequency performance and high density. The proprietary internal insulator enables simple Structure with higher performance compared to the conventional SMPM connectors.

The best applications could be 5G complex mobile communications modules, systems and various other wireless systems.







Features

- Frequency range : DC to 26.5 GHz & 67 GHz
- High density SMT packaging available
- Push-on mating for quick installation

withwave M03-du5880-5mil

Application

- 4G, 5G Telecommunications
- Satellite Communications
- RFIC Chip set evaluation board
- High data rate ASIC and SoC EV module test





High Density Board Connector

■ Specification

Scope	Items	Specification	
Electrical	Freq. range	DC to 26.5 GHz (ST17MS001) DC to 67.0 GHz (ST17MS002)	
	Impedance	50 Ohm	
	VSWR(RL, Typical)	1.43:1 (-15dB) to 26.5 GHz (ST17MS001) 1.43:1 (-15dB) to 40 GHz (ST17MS002) 1.93:1 (-10dB) to 67 GHz (ST17MS002)	
Material	Mating Cycles	Full Detent : 100 (min)	
	Typical Engage (Disengage) Force	Full Detent: 4lbs typ.(6lbs typ.)	
	Operating Temperature	-40~+125°C	

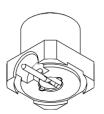
^{*} RoHS Compliant

Ordering Information

Application	Freq.(GHz)	Туре	Part No.
SMPM, Straight Plug, PCB (Full Detent)	DC to 26.5	Male	ST17MS001
SMPM, Straight Plug, PCB (Full Detent)	DC to 67.0	Male	ST17MS002







High Density Board Connector



Test Result

SMPM Connector

Substrate: RT/DU5880 (5 mil)

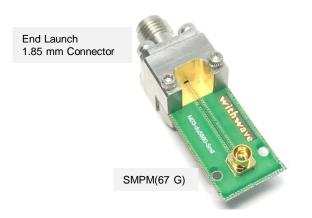
Part No.: ST17MS001



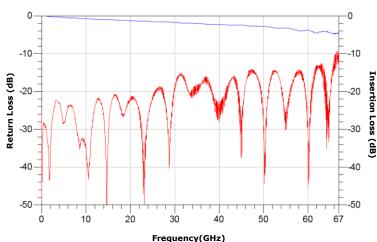
Freq.: 10 MHz to 26.5 GHz -10 Return Loss (dB) Insertion Loss (dB) -30 -40 -50 20.0 25.0 0.0 5.0 10.0 15.0 Frequency(GHz)

Substrate: RT/DU5880 (5 mil)

Part No.: ST17MS002



Freq.: 10 MHz to 67 GHz



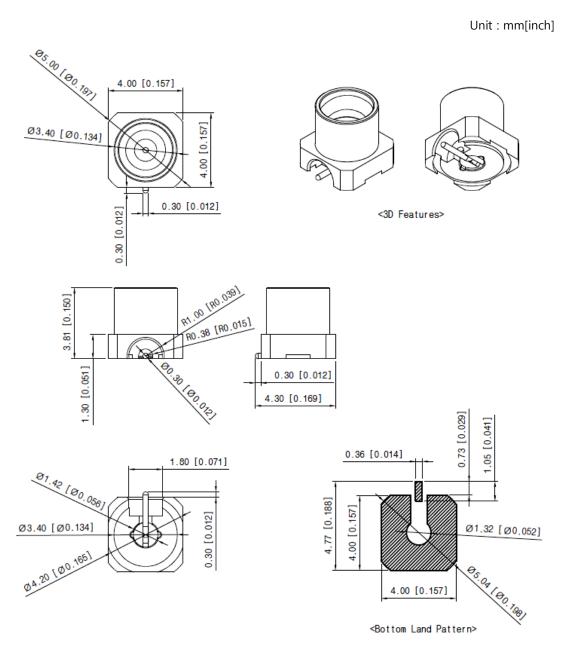
High Density Board Connector



Drawing

SMPM Connector

Part No.: SM17MS001



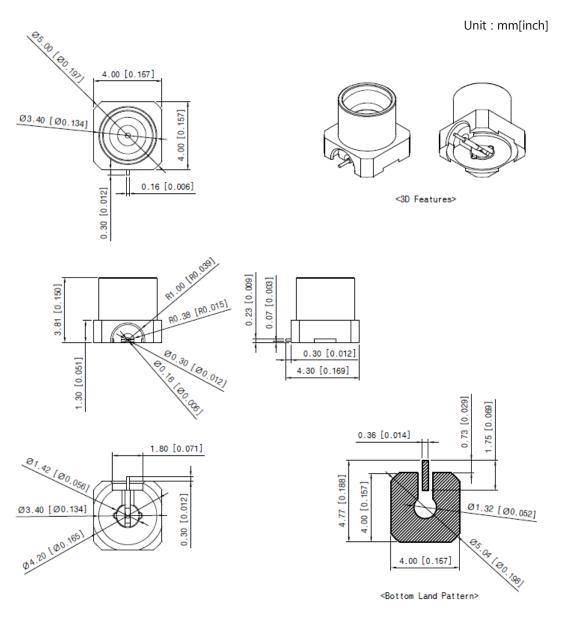
High Density Board Connector



Drawing

SMPM Connector

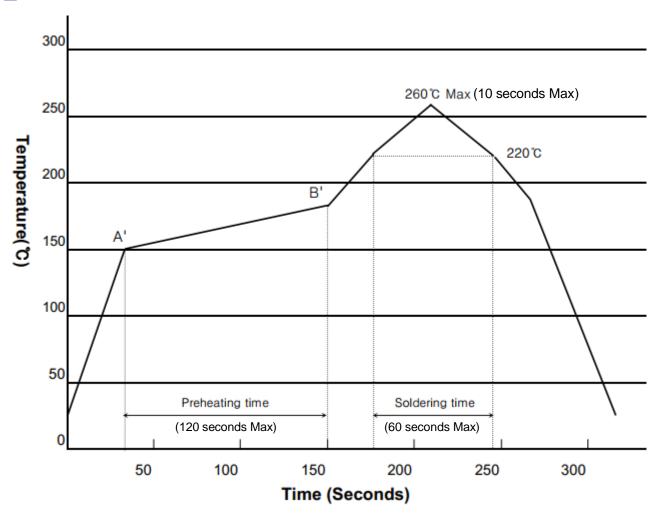
Part No.: SM17MS002



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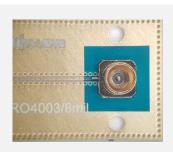
High Density Board Connector

Recommended Reflow Profile



Test Condition

- Reflow System: IR reflow
- Solder: Cream type Sn / 3 Ag / 0.5 Cu, Flux content 11%wt (SMIC M705 Lead free or Halogen free)
- Metal mask thickness: 0.08 mm
- Preheating time: 150°C~190°C, Max 120seconds
- Soldering time: 260°C Max, 220°C Min, Max 60 seconds (N2 condition recommended)

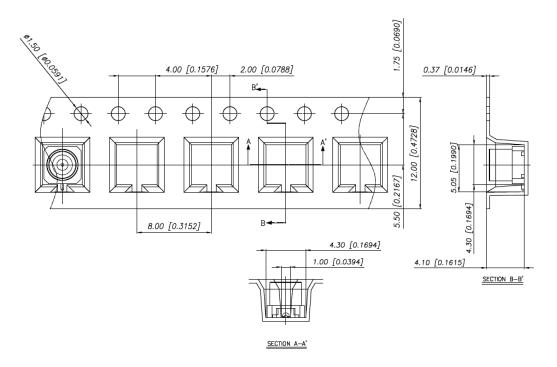


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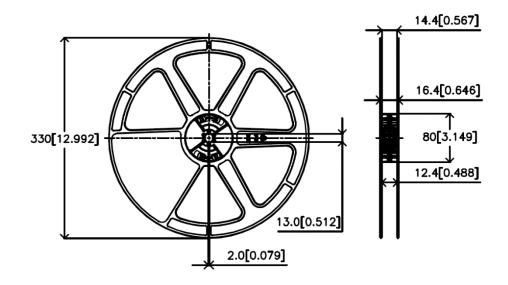
High Density Board Connector

Packaging Information

Unit: mm[inch]



Packing Qty 2,000 ea/Reel





High Density Board Connector

Revision History

Revision	Date	Changes
Ver 1.0	2019-09-01	Released SMPM Connectors